Safe Harbor

During the course of this meeting, we may make projections or other forward-looking statements regarding future events or the future financial performance of the Company and the industry. We wish to caution you that such statements are predictions and that actual events or results may differ materially. We refer you to the documents the Company files on a consolidated basis from time to time with Securities and Exchange Commission, specifically the Company’s most recent Form 10-K and Form 10-Q. These documents contain and identify important factors that could cause the actual results for the Company on a consolidated basis to differ materially from those contained in our projections or forward-looking statements. These certain factors can be found at http://www.micron.com/certainfactors. Although we believe that the expectations reflected in the forward-looking statements are reasonable, we cannot guarantee future results, levels of activity, performance or achievements. We are under no duty to update any of the forward-looking statements after the date of the presentation to conform these statements to actual results.
2011 Micron Winter Analyst Conference

Steve Appleton
Chairman and CEO
Micron Evolution

- Recognized Need for Strategic Shift
- Leverage Technology Expertise
- Pursue Efficient Capital Deployment (cheap assets with scale & partnerships)
- Product Portfolio Expansion

- Decrease in Long Term DRAM Annual Bit Growth to < 50% year
- First Bankruptcy and Liquidation of a DRAM Company in History
- Customer Consolidation in Computing
- Government Subsidized Companies
Application Revenue Diversification

Includes DRAM, NAND, and NOR; NOR does not include purchase accounting adjustments
Segment Revenue Diversification

<table>
<thead>
<tr>
<th>Year</th>
<th>DRAM</th>
<th>NAND</th>
<th>NOR</th>
<th>Imager</th>
</tr>
</thead>
<tbody>
<tr>
<td>FY 2006</td>
<td>77%</td>
<td>6%</td>
<td>17%</td>
<td>12%</td>
</tr>
<tr>
<td>FY 2007</td>
<td>65%</td>
<td>23%</td>
<td>11%</td>
<td>11%</td>
</tr>
<tr>
<td>FY 2008</td>
<td>54%</td>
<td>35%</td>
<td>11%</td>
<td>11%</td>
</tr>
<tr>
<td>FY 2009</td>
<td>50%</td>
<td>39%</td>
<td>5%</td>
<td>4%</td>
</tr>
<tr>
<td>FY 2010</td>
<td>57%</td>
<td>34%</td>
<td>5%</td>
<td>4%</td>
</tr>
<tr>
<td>FQ1 2011</td>
<td>47%</td>
<td>31%</td>
<td>19%</td>
<td>3%</td>
</tr>
</tbody>
</table>

% of Micron Total Revenues

FY 2006

FY 2007

FY 2008

FY 2009

FY 2010

FQ1 2011
DRAM Solutions Group

Brian Shirley
Vice President
Cloud computing and virtualization driving need for more cores

Further drives DRAM density, performance needs, and power concerns

Intel’s Romley launch in 2H’11

High-end routers running past traditional DRAM limits

Customer premise equipment market exploding (CPE)

Exploding demand from Storage market

Visual enhancements are driving increased DRAM needs

New game console planning underway with unparalleled speed needs

Speed requirements increasing to 2Gbps +…

PC’s converted to DDR3 and up to 4GB

Tablets using DDR2 today, soon DDR3 and early DDR4 due to power

Sandy Bridge integrates GPU on to CPU, pushing up main memory needs
### DRAM Solutions Group - DSG

<table>
<thead>
<tr>
<th>Server</th>
<th>Networking &amp; Storage</th>
<th>Graphics</th>
<th>Personal Computing</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cloud computing and virtualization driving need for more cores</td>
<td>High-end routers running past traditional DRAM limits</td>
<td>Visual enhancements are driving increased DRAM needs</td>
<td>PC’s converted to DDR3 and up to 4GB</td>
</tr>
<tr>
<td>Further drives DRAM density, performance needs, and power concerns</td>
<td>Customer premise equipment market exploding (CPE)</td>
<td>New game console planning underway with unparalleled speed needs</td>
<td>Tablets using DDR2 today, soon DDR3 and early DDR4 due to power</td>
</tr>
<tr>
<td>Intel’s Romley launch in 2H’11</td>
<td>Exploding demand from Storage market</td>
<td>Speed requirements increasing to 2Gbps +…</td>
<td>Sandy Bridge integrates GPU on to CPU, pushing up main memory needs</td>
</tr>
</tbody>
</table>

Increasing need for high density, high speed, low power DRAM solutions:

**Micron’s DRAM portfolio drives the world’s infrastructure**
Leading in New Applications: **Tablets**

**Tablet Shipment Growth**

- **2010**
- **2011**
- **2012**
- **2013**
- **2014**

**Source:** Gartner 4Q’10; Micron Market Research

**One of the Hottest Items at CES 2011**

- **2011 Tablet shipments projected to grow 3x**
- **Projected to out-ship desktops by 2014**
- **Utilize a wide range of DRAM**
- **Power is Key for Tablets**
Leading with New Interfaces: DDR4
...optimized for power and performance

**DDR4 Market Introduction**

<table>
<thead>
<tr>
<th>Year</th>
<th>SDR</th>
<th>DDR</th>
<th>DDR2</th>
<th>DDR3</th>
<th>DDR4</th>
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</thead>
<tbody>
<tr>
<td>2009</td>
<td></td>
<td></td>
<td>100%</td>
<td>0%</td>
<td>0%</td>
</tr>
<tr>
<td>2010</td>
<td>20%</td>
<td>80%</td>
<td>0%</td>
<td>0%</td>
<td>0%</td>
</tr>
<tr>
<td>2011</td>
<td>40%</td>
<td>60%</td>
<td>0%</td>
<td>0%</td>
<td>0%</td>
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<tr>
<td>2012</td>
<td>60%</td>
<td>40%</td>
<td>0%</td>
<td>0%</td>
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<tr>
<td>2013</td>
<td>80%</td>
<td>20%</td>
<td>0%</td>
<td>0%</td>
<td>0%</td>
</tr>
<tr>
<td>2014</td>
<td>100%</td>
<td>0%</td>
<td>0%</td>
<td>0%</td>
<td>0%</td>
</tr>
</tbody>
</table>

**The next major standard**

**DDR4 introduction expected in 2012**
- Main interest in power sensitive applications

**Key improvements over DDR3**
- Higher Bandwidth: Up to 3.2 Gbps
- Power Consumption: 1.2V drives big improvement
- High Density: 128Gb in single-stack, single-load

**Ideal Memory for variety of applications**
- Server ideal due to power & performance benefits
- Tablet PC benefit from low voltage
- Fast introduction in Notebooks expected

**Micron fully committed to DDR4 introduction**
- Driving JEDEC standardization
- Early development of DDR4 with introduction in 1H’2012

Source: Gartner 4Q’10
Leading with New Technology: 3x nm

Improved Performance, Power-efficiency and Cost

- High-performance 1Gb, 2Gb and 4Gb DDR3 products for broad range of applications across all market segments
- Further power reductions and functionality down to 1.2V
- ~50% more 4Gb chips per wafer versus 42nm
- Enabling standard module densities of up to 64GB
- Lead Technology for DDR4 Introduction

Key Features and Portfolio Roll-out

- Key features:
  - High speed operation up to 1866 Gbps DDR3 and 2400 Gbps DDR4
  - Fully 1.50V and 1.35V compatible DDR3 and 1.20V on DDR4
  - Technology and circuit design related power improvements for best-in-class power
- First samples available now
Leading with New Form Factors: **LRDIMM**

**Fully Populated System**

- **50% Higher System Capacity**
- **67% Higher Bandwidth**

**Higher-density modules at improved performance**

- IT, virtualization, and datacenters need for higher density
- Standard DIMMS limit scaling of capacity and performance
- Micron’s new LRDIMM technology delivers a high performance, cost effective solution to address today’s IT system challenges

**Roll-out of Portfolio**

- Broad Standard and VLP Portfolio
- Module Densities up to 64GB
- Samples available now

**Happening Now**
Leading with New Products: **RLDRAM3**

**The best low-latency DRAM gets better**

- Unprecedented performance for high-end networking
- Comparable to SRAM access time at superior cost and density
- Easy transition path from RL2 platforms
- High interest of customers and key enablers

**Extended success of RLDRAM2 with RLDRAM3**

- Improved performance:
  - random access time down to 10ns write and 2.5ns read
  - doubled sustainable bandwidth of 2133 Gbps
  - power-efficiency and high memory density
- Memory densities of 576Mb and 1.1Gb
- Samples available mid 2011, production in 2H 2011
- 2\textsuperscript{nd} source partner identified

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Leading with New Innovations

Revolutionary Approach to Break Through the “Memory Wall”

- Evolutionary DRAM roadmaps hit limitations of bandwidth and power efficiency
- Micron introduces a new class of memory: **Hybrid Memory Cube**
- Unique combination of DRAMs on Logic smashes through the wall

Key Features and Roll-Out

- How did we do it?
  - Micron-designed logic controller
  - High speed link to CPU
  - Massively parallel “Through Silicon Via” connection to DRAM

- Unparalleled performance:
  - Up to 20X the bandwidth of a full DDR3 DIMM
  - Using a 10th of the power per bit
  - Occupying an 8th of the space of an RDIMM

- Targeting high performance computing and networking, eventually migrating into computing and consumer
Hybrid Memory Cube Prototype
DRAM Solutions Group

► Focus on segments driven by exploding bandwidth and computing needs

► Broad product portfolio focused on optimal solutions across performance, power, and density

► Leadership in next generation solutions, driving enhanced margin opportunities
NAND Solutions Group

Glen Hawk
Vice President
NAND Market Diversity

Source: Gartner 4Q10; Cards included in Mobile and DSC
Micron’s Business Units focused on NAND

Source: Gartner 4Q10; Cards included in Mobile and DSC

SSDs $2.5B market in 2011 going to $7B+ in 2014

NAND Solutions Group

Wireless Solutions Group

Embedded Solutions Group

0% 10% 20% 30% 40% 50% 60% 70% 80% 90% 100%

February 21, 2011
Digitization of Photography
Digitization of Photography
Transformation of File Storage
Revolution of Music
Revolution of Music
The Next Revolution: Computing
The Next Revolution: Computing

Micron ReadlSSD™
C400 for Client
P300 for Enterprise

February 21, 2011
NAND in New Applications

Source: Gartner 4Q10; Cards included in Mobile and DSC

February 21, 2011
Enterprise Commands Significant ASP Upside

Source: IDC 3Q10
Data based on publically available information
NAND System Solution Leadership

Client SSD Accolades – C300/C400

Enterprise SSD Accolades – P300

“Dubbed RealSSD P300, this new series comes out of the gates with SATA 6Gbps support -- a first ever for the enterprise market…”

“…delivering 44,000 IOPS for random reads and 16,000 IOPS for random writes to target demanding enterprise applications.”

“All in all, the P300 deserves a strong look when trying to improve server performance.”

“…enterprise SSD suppliers lacking a fab partnership, who buy flash chips on the general market, may be at a disadvantage…”

“Memory & Storage: Micron Technology C300 and P300 solid-state drives.”
Enterprise HDD and SSD Revenue

Sources: iSuppli 4Q10; IDC 3Q10; Micron Market Research
NAND Solutions Group

► Business unit dedicated to the rapidly growing NAND data storage market

► Exploiting technology leadership, from Silicon to Systems

► Targeting incremental margin opportunities in premium segments, as a complete storage system provider
Wireless Solutions Group

Mario Licciardello
Vice President
Market Dynamics

Segmentation

<table>
<thead>
<tr>
<th>Category</th>
<th>ASP</th>
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<tbody>
<tr>
<td>SmartPhone &amp; Premium</td>
<td>&gt;$150</td>
</tr>
<tr>
<td>Entry</td>
<td>&lt; 150$</td>
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</tbody>
</table>

Technology Trends

<table>
<thead>
<tr>
<th>Technology</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Growth accelerator for both NAND and DRAM (LPDDDR1→LPDDDR2)</td>
<td></td>
</tr>
<tr>
<td>High Volume, long term market for NOR/PSRAM &amp; Growth Driver for PCM &amp; Low Density LPDDDR2</td>
<td></td>
</tr>
</tbody>
</table>

Source: iSuppli 4Q10; Flash memory forecast 2012 and beyond and DRAM forecast from Micron WSG Q4 2010

February 21, 2011
Mobile Memory Market

- **NAND Market strong growth**
  - Density (GB) growing faster than litho migration

- **DRAM Market sustained**
  - LPDDR1 → LPDDR2 → LPDDR3 / Wide I/O
  - Density Growth per Handset 128Mb→8Gb

- **NOR + PCM Market stable**
  - PCM compensating NOR Market erosion starting early 2012

- **PSRAM Market declining**
  - Strongly associated to low Density NOR
  - PSRAM→LPDDR

Source: iSuppli, 4Q10
Leading Wireless Memory Supplier

- Micron memory present in more than 550 million phones in 2010
- Key memory supplier of all top leading phone manufacturers
- Well positioned to capitalize on SmartPhone market growth
- Full range of optimized Memory Solutions
- Driving and committed to next generation standards
Micron Addresses All Mobile Market Sub-Segments

**Entry / Connectivity**
- NOR+ PSRAM MCP
- NOR +LPDDR MCP
- OneNAND + LPDDR MCP
- NAND + LPDDR MCP
- PCM+LPDDR2MCP*

**Smart Phones**
- NAND + LP DDR MCP
- e.MMC + LP DDR2 MCP
- e.MMC Discrete
- LP DDR1/LP DDR2 PoP
- LP DDR3*
- Wide I/O*

**Media Tablet**
- e.MMC Discrete
- LP DDR1
- LP DDR2
- LP DDR3*
- Wide I/O*

*In Design and/or Development
Industry’s Most Advanced Mobile Memory Solutions

34 / 25 nm NAND (SLC)
- 1Gb → 2Gb
- 4Gb → 16Gb

50 / 42 nm Mobile DRAM (LPDDR1 or LPDDR2)
- 256Mb → 1Gb
- 2Gb → 4Gb

25 nm e.MMC4.41
- 512MB - 2GB (SLC)
- 4GB - 32GB (MLC)

NAND MCP Packaging Options
- SLC NAND + LPDDR1/2
- e.MMC4.41 + LPDDR1/2

65 / 45 nm NOR
- 32 Mb → 256Mb
- 512 Mb → 1Gb

50 nm Mobile RAM
- 16Mb → 128Mb PSRAM
- 128Mb → 512Mb LPDDR

NOR MCP Packaging Options
- NOR + PSRAM
- NOR + LPDDR

Mobile DRAM Discrete LPDDR1 or LPDDR2 (POP)
e.MMC 4.41 Discrete (BGA)
Entry Segment - Convergence to PCM

Benefits

- Reduces PCB complexity & cost
- Long term cost reduction path
- Lower BOM Cost
- Lower Power Consumption
- Improved Reliability & Endurance
- Improved System performances
- Improved User experience
Smart Phone’s Dependence on NAND Leverages Micron’s Strengths

<table>
<thead>
<tr>
<th>Category / 2011 needs</th>
<th>Density</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Raw NAND</td>
</tr>
<tr>
<td>High-end Smartphone</td>
<td>4-16Gb</td>
</tr>
<tr>
<td>Low-end Smartphone</td>
<td>4Gb</td>
</tr>
<tr>
<td>Feature Phone</td>
<td>1-2Gb</td>
</tr>
</tbody>
</table>
Tablets, the Next Major Opportunity

- **Strong Market Reaction**
  - Expected 57Mu Tablet in ‘11, > 100Mu expected in 2012

- **Total Convergence between Computing & Consumer in Mobile Environment**
  - Connectivity & Mobility are the Key success factors

- **Mobile BOM fully supported by Micron’s Memory Portfolio:**
  - LPDDR1/2: 4Gb+ → LPDDR3, Wide I/O
  - e.MMC: 32GB+ → UFS
  - System Memory for 3G+ modem NAND / NOR → PCM

Source: iSuppli, 4Q10
Wireless Solutions Group

► Industry’s broadest portfolio of DRAM, NAND, and NOR products to address the wireless market

► Targeting growth and market share opportunities in smart phones and tablets

► Focusing on technology leadership, customer satisfaction, and execution excellence for margin optimization across the spectrum of wireless markets
Embedded Solutions Group

Tom Eby
Vice President
The Embedded Memory Market

Segment Diversity
- Automotive
- Consumer
- Networking
- PC (NOR)
- IMM*

Technology Diversity
- DRAM
- NAND
- NOR

2011 $9.5B Opportunity

Customer Diversity
- 3000+ Customers
- Top 50 Customers

Sources: iSuppli, Micron Market Research

*IMM: Industrial, Medical, Mil/Aero
Need for Leading Edge Technology AND Longevity

Mainstream Products
- ESG: Consumer, PC
- DSG: Server, Networking
- NSG: Storage, SSD
- WSG: Smart Phones

Leading Edge Products Initial Ramp
- DSG: PC
- NSG: Storage, Removable, PMP

Legacy Products Long Lifecycles
- ESG: Automotive, IMM, Networking

Micron estimates

K Wafers

Leading Lithos

ESG Outlook

Legacy Lithos

Normalized to 300mm wafers

February 21, 2011
## Micron’s Competitive Advantage in the Embedded Markets

<table>
<thead>
<tr>
<th>Competitor Ranking</th>
<th>Micron</th>
<th>SAMSUNG</th>
<th>MXIC</th>
<th>Hynix</th>
<th>SPANSION</th>
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<tr>
<td><strong>Product Line Breadth</strong></td>
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<td><strong>Segment Focus</strong></td>
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<td><strong>Longevity</strong></td>
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<td><strong>Cost</strong></td>
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<td>🟢</td>
<td>🟢</td>
</tr>
</tbody>
</table>
Embedded Applications

Automotive: Infotainment Drives Growth

- 2011
- 2012
- 2013

- Infotainment
- Other Automotive Segments

IMM: $2B Market, New Focus for Micron

- 2011
- 2012
- 2013

- Medical
- Mil/Aero
- Industrial

Networking: Wireless Data Drives Bit Growth

- 2011
- 2012
- 2013

- DRAM
- NAND
- NOR

Consumer: Explosive NAND/DRAM Bit Growth

- 2011
- 2012
- 2013

- NAND
- DRAM
- NOR

Sources: iSuppli, Infonetics, Micron Market Research

February 21, 2011
Micron’s Strategy to Win in Embedded

Product Breadth
Micron’s Strategy to Win in Embedded

Technology Leadership
Micron’s Strategy to Win in Embedded

Stability
Micron’s Strategy to Win in Embedded

Trusted Memory Advisor
Embedded Solutions Group

► Targeting growth opportunities in this high-margin segment addressing a large and diverse customer base

► Broad product portfolio and technology leadership across DRAM, NAND, and NOR

► Strong customer support capabilities with supply stability and world-class service for direct and indirect sales
Efficient Operating Model

Mark Durcan
President and COO
Organization Structure

Chairman & CEO

President & COO

DRAM Solutions

NAND Solutions

Embedded Solutions

Wireless Solutions

WW Sales

WW Operations, Procurement

Memory Architecture, Process R&D, Engineering

Corp. Dev., Finance, HR, Integration, Legal

February 21, 2011

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Efficient and Effective Partnerships

- Micron
- Aptina
- MP MASK
- inotera
- transform solar
IM Flash Singapore Update

Additional capacity is dependent on market conditions.
25nm NAND Prime Die Wafer Map

IMFS 97% Yield 25nm Wafer
Inotera Update

Source: Company Data
Manassas Fab
MTV Capacity

200mm includes DRAM and NOR 200mm Capacity
Micron Fab Capacity

200mm includes DRAM and NOR 200mm Capacity
Industry-Leading Advanced Memory Products

- **Micron**
  - **64Gb 20nm NAND**
    - 1XYmm²
  - **4Gb 3x nm DRAM**
    - 38mm²
- **Micron**
  - **4Gb 45 nm NOR**
    - 8Xmm²

Images have been intentionally altered for IP protection
Emerging Memory Strategy

- A very large number of emerging memory technologies with different strengths (table below)
- Careful evaluation, strategic partnerships, and internal evaluations to achieve successful positioning

<table>
<thead>
<tr>
<th>Data Retention</th>
<th>NAND</th>
<th>PCM</th>
<th>PCMS</th>
<th>MVO</th>
<th>CBRAM</th>
<th>STT-RAM</th>
<th>FeRAM</th>
<th>MRAM</th>
<th>Molecular</th>
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</thead>
<tbody>
<tr>
<td>Bit Density (Cost)</td>
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<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
</tr>
<tr>
<td>FeRAM</td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
</tr>
<tr>
<td>MRAM</td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
</tr>
<tr>
<td>Molecular</td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
<td><img src="Green.png" alt="Green" /></td>
</tr>
</tbody>
</table>
Micron Global Sales Channels

- Optimized to support four business units
- Support diverse and differentiated businesses
- Covering the full spectrum of available sales channels
Operations

► Scaling and technology development through partnerships

► Cost reduction runway

► Advanced technology leadership

► Sales channels optimized to support diverse and differentiated businesses
Financial Strength and Leverage

Ron Foster
CFO
Micron Business Model

**Actions**
- Product Line Expansion
- Business Unit Focus
- JV Operating Model

**Competitive Position**
- Broader Market Access & Diversification
- Accelerated Technology Deployment
- Increased Capital Efficiency & Scale

**Results**
- Accelerated Growth
- Expanded Margins
- Broader Customer Engagement
Micron’s Business Unit Structure

<table>
<thead>
<tr>
<th>Business Units by Market</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>DRAM Solutions Group</strong></td>
</tr>
<tr>
<td>DRAM only</td>
</tr>
<tr>
<td>High-volume DRAM sold to:</td>
</tr>
<tr>
<td>• PC</td>
</tr>
<tr>
<td>• Consumer Electronics</td>
</tr>
<tr>
<td>• Networking</td>
</tr>
<tr>
<td>• Server</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th><strong>NAND Solutions Group</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td>NAND only</td>
</tr>
<tr>
<td>High-volume NAND sold to:</td>
</tr>
<tr>
<td>• Data Storage</td>
</tr>
<tr>
<td>• Personal Music Players</td>
</tr>
<tr>
<td>• Foundry sales to Intel (IMFT)</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th><strong>Embedded Solutions Group</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td>DRAM, NAND, NOR</td>
</tr>
<tr>
<td>Sold to:</td>
</tr>
<tr>
<td>• Automotive</td>
</tr>
<tr>
<td>• Industrial</td>
</tr>
<tr>
<td>• Networking</td>
</tr>
<tr>
<td>• Server</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th><strong>Wireless Solutions Group</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td>DRAM, NAND, NOR</td>
</tr>
<tr>
<td>Sold to:</td>
</tr>
<tr>
<td>• Mobile</td>
</tr>
</tbody>
</table>

NOR, NAND to:
• Consumer Electronics
• Networking
• PC, Server

February 21, 2011
FQ1’11 by Business Unit
( Estimate)

- WSG: 23%
- NSG: 22%
- ESG: 12%
- Other: 3%

Revenue
## Manufacturing and Technology JVs

<table>
<thead>
<tr>
<th>NAND</th>
<th>Ownership</th>
<th>Output Share</th>
<th>Output Share</th>
</tr>
</thead>
<tbody>
<tr>
<td>Micron</td>
<td>51%</td>
<td>51%</td>
<td>49%</td>
</tr>
<tr>
<td>Intel</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Micron</td>
<td>78%</td>
<td>78%</td>
<td>22%</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>DRAM</th>
<th>Ownership</th>
<th>Output Share</th>
<th>Output Share</th>
</tr>
</thead>
<tbody>
<tr>
<td>Micron</td>
<td>30%</td>
<td>50%</td>
<td>50%</td>
</tr>
<tr>
<td>Micron</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Nanya</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

1. With delay of 12 months following change in ownership
2. As of December 2010
3. Not tied to Ownership
Joint Venture Strategy
Leverage through Scale and Shared Investment

R&D 2010

- DRAM Partner Funding*: $135M
- NAND Partner Funding: $104M
- Micron R&D: $624M

* DRAM partner funding includes $84M for royalties and other R&D services recorded as 2010 revenue
TECH Buyout

Balance Sheet Impact

<table>
<thead>
<tr>
<th></th>
<th>Assets</th>
<th>Equity</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cash</td>
<td>$(159)</td>
<td></td>
</tr>
<tr>
<td>Non-controlling Interest</td>
<td></td>
<td>$224</td>
</tr>
<tr>
<td>Additional Paid in Capital</td>
<td></td>
<td>$(65)</td>
</tr>
<tr>
<td>Total $M</td>
<td>$(159)</td>
<td>$159</td>
</tr>
</tbody>
</table>

Small Impact to P&L (Minority Interest)

<table>
<thead>
<tr>
<th></th>
<th>Q1 ’10</th>
<th>Q2 ’10</th>
<th>Q3 ’10</th>
<th>Q4 ’10</th>
<th>2010</th>
<th>Q1 ’11</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>$(2)</td>
<td>$14</td>
<td>$21</td>
<td>$17</td>
<td>$50</td>
<td>$17</td>
</tr>
</tbody>
</table>
Debt to Capital Ratio
(Most Recent Quarter)

Debt to Capital = (LT Debt + Current Portion of LT Debt + ST Borrowings) / (LT Debt + Current Portion of LT Debt + ST Borrowings + Balance Sheet Equity + Minority Interest)

<table>
<thead>
<tr>
<th>Company</th>
<th>Debt to Capital</th>
</tr>
</thead>
<tbody>
<tr>
<td>Micron FQ1-11</td>
<td>15%</td>
</tr>
<tr>
<td>Winbond CQ4-10</td>
<td>35%</td>
</tr>
<tr>
<td>Hynix CQ4-10</td>
<td>42%</td>
</tr>
<tr>
<td>Elpida CQ4-10</td>
<td>56%</td>
</tr>
<tr>
<td>Inotera CQ4-10</td>
<td>57%</td>
</tr>
<tr>
<td>Powerchip CQ3-10</td>
<td>60%</td>
</tr>
<tr>
<td>Nanya CQ3-10</td>
<td>66%</td>
</tr>
<tr>
<td>ProMOS CQ3-10</td>
<td>82%</td>
</tr>
</tbody>
</table>

Source: Company Data, Micron Market Research
Net Cash Position
(Most Recent Quarter)

Net Cash = Gross Cash - (Long-term Debt + Short-term Borrowings + Current Portion of LT Debt)

<table>
<thead>
<tr>
<th>Company</th>
<th>Quarter</th>
<th>Net Cash (in Millions of US$)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Micron</td>
<td>FQ1-11</td>
<td>$595</td>
</tr>
<tr>
<td>Winbond</td>
<td>CQ4-10</td>
<td>-$510</td>
</tr>
<tr>
<td>Powerchip</td>
<td>CQ3-10</td>
<td>-$1,771</td>
</tr>
<tr>
<td>ProMOS</td>
<td>CQ3-10</td>
<td>-$1,825</td>
</tr>
<tr>
<td>Nanya</td>
<td>CQ3-10</td>
<td>-$1,856</td>
</tr>
<tr>
<td>Inotera</td>
<td>CQ4-10</td>
<td>-$2,077</td>
</tr>
<tr>
<td>Elpida</td>
<td>CQ4-10</td>
<td>-$3,190</td>
</tr>
<tr>
<td>Hynix</td>
<td>CQ4-10</td>
<td>-$3,215</td>
</tr>
</tbody>
</table>

Source: Company Data, Micron Market Research

February 21, 2011
Cash to Short-Term Debt
(Most Recent Quarter)

Cash to ST Debt = Cash / (Short-term Borrowings + Current Portion of LT Debt)

Source: Company Data, Micron Market Research

Note: Short-term debt includes lease obligations
Revenue by Geography
Micron FY’10 Sales Revenue

Asia¹
70%

Americas²
21%

Europe
9%

Source: Micron Technology, Inc. 2010 Form 10-K
1 – Asia includes China, Asia Pacific, Malaysia, and Taiwan
2 – Americas includes United States and Other

February 21, 2011
Micron’s Total Wafer Production by Geography

- **Americas**: 37%
- **Europe**: 3%
- **Japan**: 4%
- **Asia/Pac**: 56%

**CY2008**

**CY2012F**

February 21, 2011
FY2011 CapEx Guidance

$2.4B - $2.9B

- NAND
- DRAM
- NOR & Other
Financial Strength and Leverage

- Cost and growth leverage with partnership models and increasingly low-cost manufacturing base

- Capital deployment focused on high growth NAND market with positive P&L implications going forward

- Strong financial position versus competitors
Memory Leadership

Steve Appleton
Chairman and CEO
DRAM vs NAND Market Development

Source: Gartner 4Q10
Memory Industry CapEx

Millions of $US

Source: Gartner 4Q10
Forecasts Point to Technology as the Main DRAM Industry Supply Growth Driver

Sources: Gartner, IDC, iSuppli, Merrill Lynch, and Credit Suisse from 2006-2008; Average of Gartner, IDC, and iSuppli 2009-2010, Micron Forecast, Finance Strategy Group – drivers split
Forecasts see Technology as the Main NAND Industry Supply Growth Driver

Sources: Gartner, IDC, iSuppli, Merrill Lynch, and Credit Suisse from 2006-2008; Average of Gartner, IDC, and iSuppli 2009-2012, Finance Strategy Group – drivers split